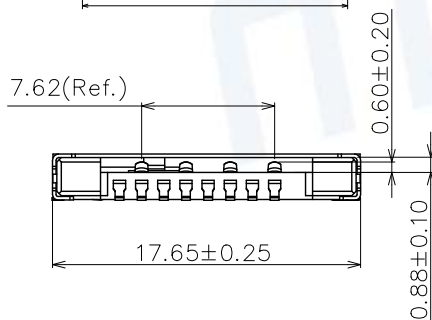
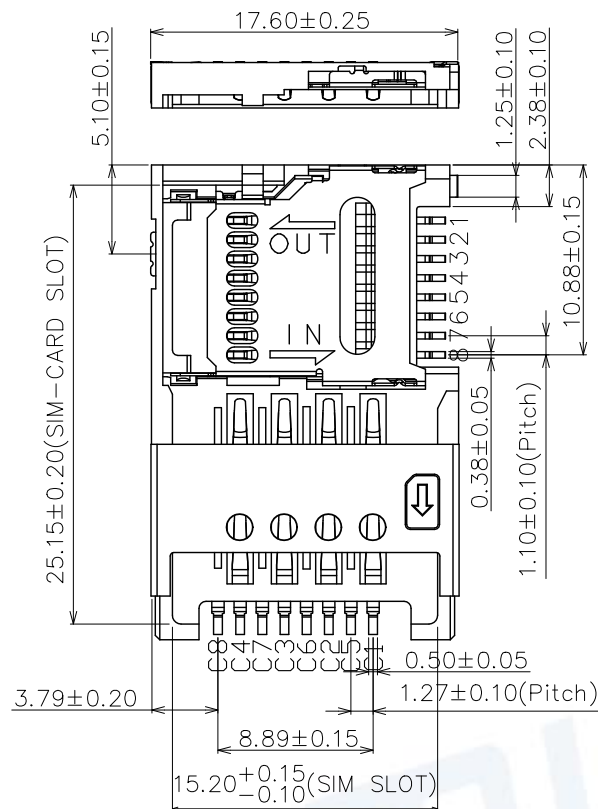




Micro SD CARD		SIM CARD	
Pin No.	NAME	Pin No.	NAME
1	DAT2	C1	VCC
2	CD/DAT3	C2	RST
3	CMD	C3	CLK
4	VDD	C4	Reserved
5	CLK	C5	GND
6	VSS	C6	VPP
7	DAT0	C7	I/O
8	DAT1	C8	Reserved

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 27.20LX17.68WX2.65H mm

Weight: Approx 1.22±0.2g

Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical, 100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C, 30sec.Max

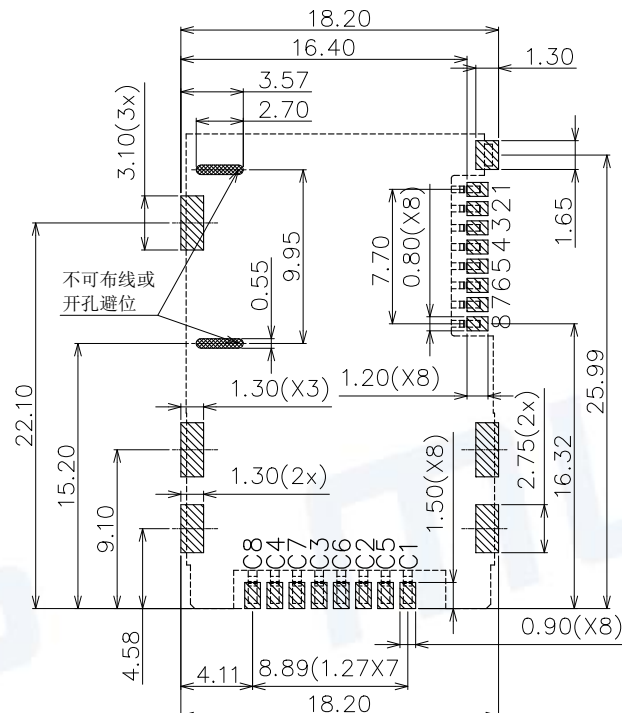
IR reflow: 260°C, 10sec.Max

Manual soldering: 370°C, 3sec.Max

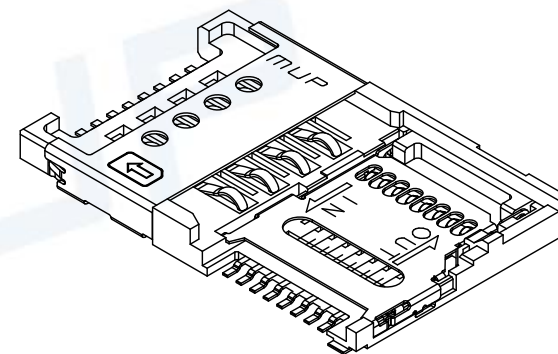
4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity: 10%~+95%RH



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE±0.05)



ITEM	PART NAME	Q'TY	MATERIAL	FINISH	
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0	
2	SIM TERMINAL	8	Copper Alloy	Contact area:5μ "Au plated Solder tail:G/F Au plated Under plated:50 μ "Ni plated	
3	SIM SHELL	1	Stainless Steel	Contact area:1 μ "Au plated Under plated:50 μ "Ni plated	
4	Micro SD TERMINAL	8	Copper Alloy	Contact area:5 μ "Au plated Solder tail:G/F Au plated Under plated:50 μ "Ni plated	
5	HOLDER	1	Copper Alloy	Solder tail:G/F Au plated Under plated:50 μ "Ni plated	
6	Micro SD SHELL	1	Stainless Steel		
Unless otherwise specified, other tolerance are:			MUP[®] MUP INDUSTRIAL CO.,LTD.		
X ±0.35		X* ±5*	NAME: 2 in 1 Card Connector		
X.X ±0.25		X.X* ±4*	MODEL NO: MUP M619-2		
X.XX ±0.15		X.XX* ±3*	TYPE : Micro SD8pin+SIM8pin		
X.XXX ±0.10		X.XXX* ±2*			
PROJ.		UNIT	SCALE	DRAWN	
	MM		1:1	huabo Dec.11.2021	
CUSTOMER DRAWING				CHECKED	Zoey Dec.11.2021
				APPROVAL	Simon Dec.11.2021
				DWG NO.: DWG-MUP-M619-002	
				SHEET	REVISION
				1/1	X1